

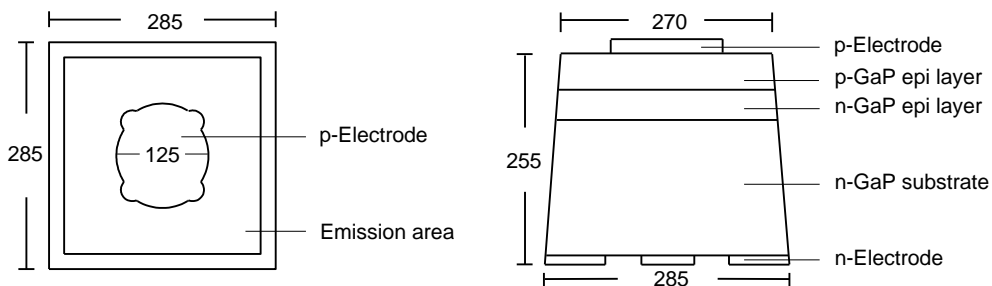
■ Features :

- GaP/GaP Epi Wafer

■ Typical Applications :

- Lamp
- SMD
- Dot Matrix
- Back Light

■ Outline Dimensions : (Unit: μm)



■ Physical Structure :

Chip dimension	Chip size	285 μm x 285 μm
	Thickness	255 μm
	Emission area	270 μm
	Bonding pad	125 μm
Electrode	Top: P (anode)	Aluminum (Gold optional)
	Backside: N (cathode)	Gold alloy
Surface condition	Frosted	

■ Electro-Optical Characteristics : ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 20 \text{ mA}$	1.80	2.20	2.60	V
Reverse Current	I_R	$V_R = 5 \text{ V}$	-	-	10	μA
Wavelength	λ_P	$I_F = 20 \text{ mA}$	-	568	-	nm
	Hue		-	573	-	
Spectral width at half height	$\Delta \lambda$	$I_F = 20 \text{ mA}$	-	30	-	nm
Luminous Intensity	I_v	$I_F = 20 \text{ mA}$	7.0	-	-	mcd

■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

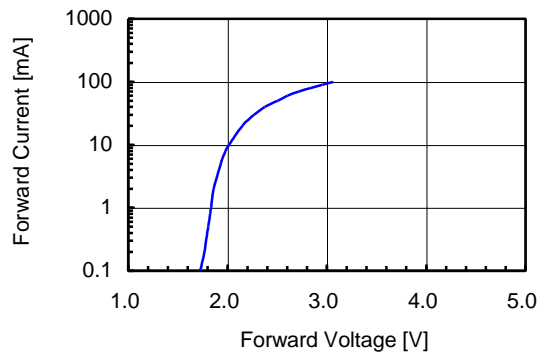


Fig 2. Relative Intensity vs. Forward Current

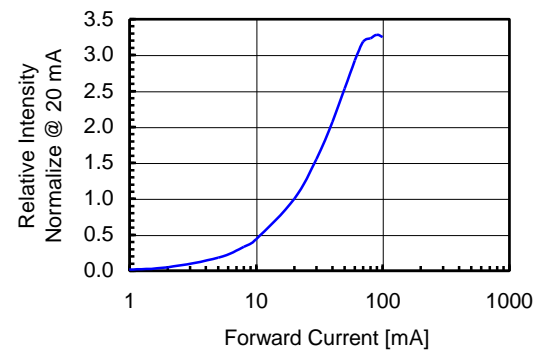


Fig 3. Forward Voltage vs. Temperature

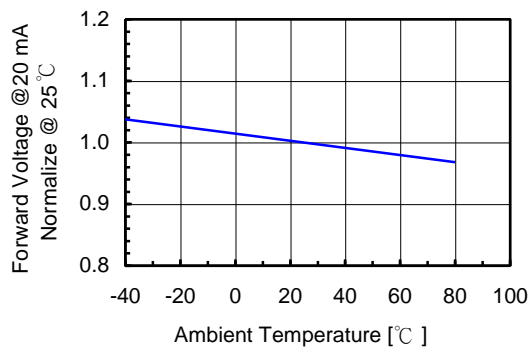


Fig 4. Relative Intensity vs. Temperature

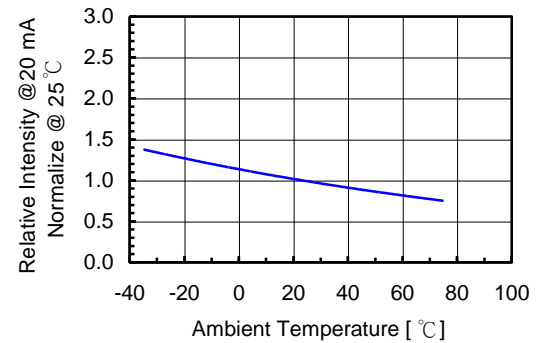


Fig 5. Relative Intensity vs. Wavelength

